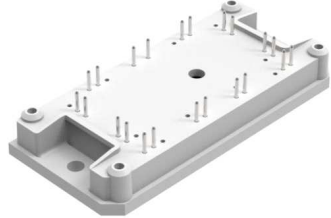
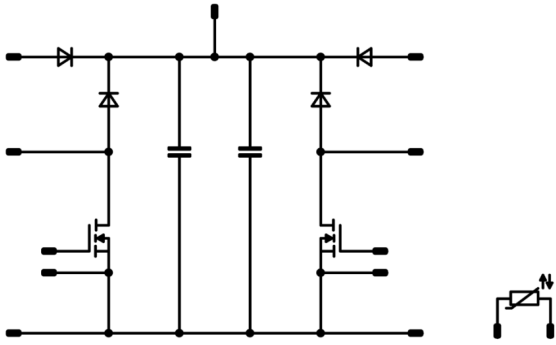




Vincotech

<i>flow</i> BOOST 1 dual SiC	1200 V / 40 mΩ
<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;"><b>Features</b></div> <ul style="list-style-type: none"> <li>High frequency SiC MOSFET</li> <li>Compact and low inductive design</li> </ul>	<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;"><b>flow 1 12mm housing</b></div> 
<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;"><b>Target applications</b></div> <ul style="list-style-type: none"> <li>Solar</li> </ul>	<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;"><b>Schematic</b></div> 
<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;"><b>Types</b></div> <ul style="list-style-type: none"> <li>10-FY12B2A040MR02-L387L63</li> </ul>	

## Maximum Ratings

$T_j = 25\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
<b>Boost Switch</b>				
Drain-source voltage	$V_{DSS}$		1200	V
Drain current	$I_D$	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	32	A
Peak drain current	$I_{DM}$	$t_p$ limited by $T_{jmax}$	137	A
Total power dissipation	$P_{tot}$	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	73	W
Gate-source voltage	$V_{GSS}$		-4/22	V
Maximum Junction Temperature	$T_{jmax}$		175	°C



Vincotech

## Maximum Ratings

$T_j = 25\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
<b>Boost Diode</b>				
Peak Repetitive Reverse Voltage	$V_{RRM}$		1200	V
Continuous (direct) forward current	$I_F$	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	48	A
Total power dissipation	$P_{tot}$	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	125	W
Maximum Junction Temperature	$T_{jmax}$		175	°C
<b>Rectifier Diode</b>				
Peak Repetitive Reverse Voltage	$V_{RRM}$		1600	V
Continuous (direct) forward current	$I_F$	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	53	A
Surge (non-repetitive) forward current	$I_{FSM}$	50 Hz Single Half Sine Wave $t_p = 10\text{ ms}$ $T_j = 150\text{ °C}$	490	A
Surge current capability	$I^2t$		1200	A <sup>2</sup> s
Total power dissipation	$P_{tot}$	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	86	W
Maximum Junction Temperature	$T_{jmax}$		150	°C
<b>DC Link Capacitance</b>				
Maximum DC voltage	$V_{MAX}$		1500	V
Operation Temperature	$T_{op}$		-55...+125	°C
<b>Module Properties</b>				
<b>Thermal Properties</b>				
Storage temperature	$T_{stg}$		-40...+125	°C
Operation temperature under switching condition	$T_{jop}$		-40...(T <sub>jmax</sub> - 25)	°C
<b>Isolation Properties</b>				
Isolation voltage	$V_{isol}$	DC Test Voltage $t_p = 2\text{ s}$	4000	V
Creepage distance			min. 12,7	mm
Clearance			9,43	mm
Comparative Tracking Index	CTI		> 200	



Vincotech

## Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		$V_{GS}$ [V]	$V_{CE}$ [V]	$I_C$ [A]	$T_j$ [°C]	Min	Typ	Max		

### Boost Switch

#### Static

Parameter	Symbol	$V_{GS}$ [V]	$V_{CE}$ [V]	$I_C$ [A]	$T_j$ [°C]	Min	Typ	Max	Unit
Drain-source on-state resistance	$r_{DS(on)}$	18		20	25 125 150		39 52 60	50	mΩ
Gate-source threshold voltage	$V_{GS(th)}$	$V_{GS} = V_{DS}$		0,01	25	2,7		5,6	V
Gate to Source Leakage Current	$I_{GSS}$	22 -4	0		25			100 -100	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	0	1200		25			10	μA
Internal gate resistance	$r_g$						7		Ω
Gate charge	$Q_g$						107		nC
Gate to source charge	$Q_{GS}$	18	600	20	25		22		
Gate to drain charge	$Q_{GD}$						41		
Short-circuit input capacitance	$C_{iss}$						1337		pF
Short-circuit output capacitance	$C_{oss}$	$f = 1$ MHz	0	800	25		76		
Reverse transfer capacitance	$C_{rss}$						27		

#### Reverse Diode Static

Parameter	Symbol	$V_{GS}$ [V]	$V_{CE}$ [V]	$I_C$ [A]	$T_j$ [°C]	Min	Typ	Max	Unit
Forward voltage	$V_{SD}$	0		20	25		3,20		V

#### Thermal

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4$ W/mK		1,31		K/W

### Boost Diode

#### Static

Parameter	Symbol	$V_{GS}$ [V]	$V_{CE}$ [V]	$I_C$ [A]	$T_j$ [°C]	Min	Typ	Max	Unit
Forward voltage	$V_F$			30	25 125 150		1,4 1,8 1,9	1,6	V
Reverse leakage current	$I_r$		1200		25			600	μA

#### Thermal

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4$ W/mK		0,76		K/W



Vincotech

## Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		$V_{GE}$ [V] $V_{GS}$ [V]	$V_{CE}$ [V] $V_{DS}$ [V]	$I_C$ [A] $I_D$ [A]	$T_j$ [°C]	Min	Typ	Max		

### Rectifier Diode

#### Static

Forward voltage	$V_F$			50	25 125		1,22 1,48	1,8	V
Reverse leakage current	$I_r$		1600		25 150			50 1100	$\mu$ A

#### Thermal

Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4$ W/mK					0,82		K/W
-------------------------------------	---------------	---	--	--	--	--	------	--	-----

### DC Link Capacitance

Capacitance	C						78		nF
Tolerance						-10		+10	%
Climatic category							55/125/56		

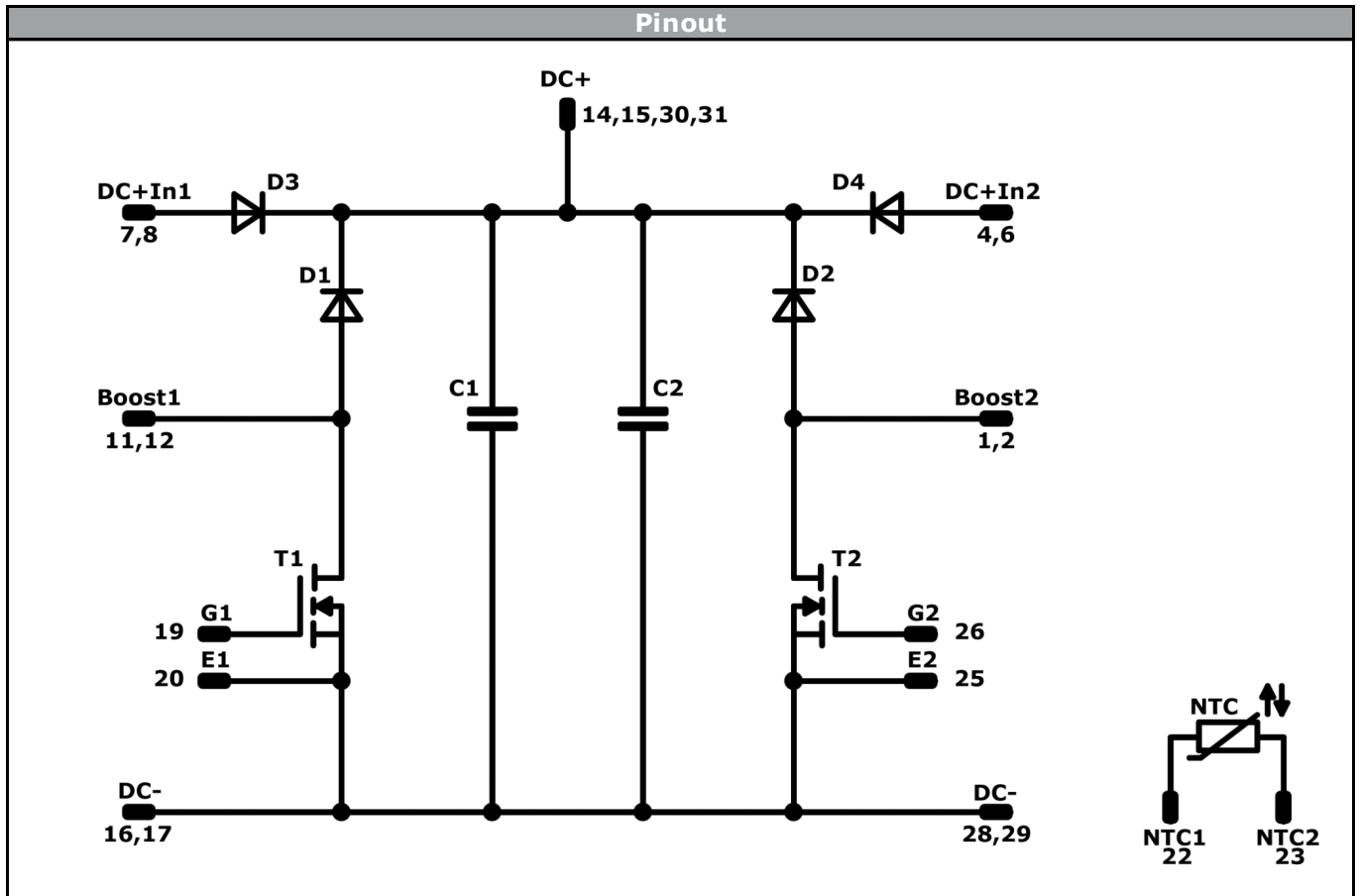
### Thermistor

Rated resistance	$R$				25		22		k $\Omega$
Deviation of R100	$\Delta_{R/R}$	$R_{100} = 1484 \Omega$			100	-5		5	%
Power dissipation	$P$				25		5		mW
Power dissipation constant					25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. $\pm 1$ %			25		3962		K
B-value	$B_{(25/100)}$	Tol. $\pm 1$ %			25		4000		K
Vincotech NTC Reference								I	





Vincotech



<b>Identification</b>					
ID	Component	Voltage	Current	Function	Comment
T1, T2	MOSFET	1200 V	40 mΩ	Boost Switch	
D1, D2	FWD	1200 V	30 A	Boost Diode	
D3, D4	FWD	1600 V	50 A	Rectifier Diode	
C1, C2	Capacitor	1500 V		DC Link Capacitance	
NTC	Thermistor			Thermistor	




Vincotech

Packaging instruction			
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ Sample

Handling instruction
Handling instructions for <i>flow 1</i> packages see vincotech.com website.

Package data
Package data for <i>flow 1</i> packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website. 

Document No.:	Date:	Modification:	Pages
10-FY12B2A040MR02-L387L63-T1-14	25 Apr. 2016		

Product status definition		
Datasheet Status	Product Status	Definition
Target	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice. The data contained is exclusively intended for technically trained staff.

**DISCLAIMER**

The information, specifications, procedures, methods and recommendations herein (together "information") are presented by Vincotech to reader in good faith, are believed to be accurate and reliable, but may well be incomplete and/or not applicable to all conditions or situations that may exist or occur. Vincotech reserves the right to make any changes without further notice to any products to improve reliability, function or design. No representation, guarantee or warranty is made to reader as to the accuracy, reliability or completeness of said information or that the application or use of any of the same will avoid hazards, accidents, losses, damages or injury of any kind to persons or property or that the same will not infringe third parties rights or give desired results. It is reader's sole responsibility to test and determine the suitability of the information and the product for reader's intended use.

**LIFE SUPPORT POLICY**

Vincotech products are not authorised for use as critical components in life support devices or systems without the express written approval of Vincotech.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in labelling can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.